

DISPLAY Elektronik GmbH

DATA SHEET

LCD MODULE

DEM 128064F1 FGH-P(RGB)

Product Specification

Version: 0

07.09.2021

GENERAL SPECIFICATION

MODULE NO. :

DEM 128064F1 FGH-P(RGB)

CUSTOMER P/N:

Version No.	Change Description	Date
0	Original Version	07.09.2021

PREPARED BY: LM

DATE: 07.09.2021

APPROVED BY: WH

DATE: 07.09.2021

CONTENTS

1. FUNCTIONS & FEATURES 2

2. MECHANICAL SPECIFICATIONS 2

3. EXTERNAL DIMENSIONS (⊕ unit: mm)..... 3

4. BLOCK DIAGRAM..... 4

5. PIN DESCRIPTION..... 5

6. ABSOLUTE MAXIMUM RATINGS 6

7. BACKLIGHT CHARACTERISTICS..... 6

8. ELECTRICAL CHARACTERISTICS 7

9. COMMAND TABLE..... 11

10.LCD ARTWORK..... 12

11.LABELLING..... 12

12. PAD CONFIGURATION& GRAPHIC DIMENSION..... 13

13. IC NO. CONFIGURATION& PAD CONFIGURATION 13

14. SEG&COM LAYOUT 14

15. IC LAYOUT 15

16. QUALITY DESCRIPTION 15

17. MODULE ACCEPTS QUALITY LEVEL (AQL). 16

18. RELIABILITY TEST..... 16

19. LCD MODULES HANDLING PRECAUTIONS 17

20. OTHERS..... 17

1. FUNCTIONS & FEATURES

I DEM 128064F1 FGH-P(RGB) Series LCD Type :

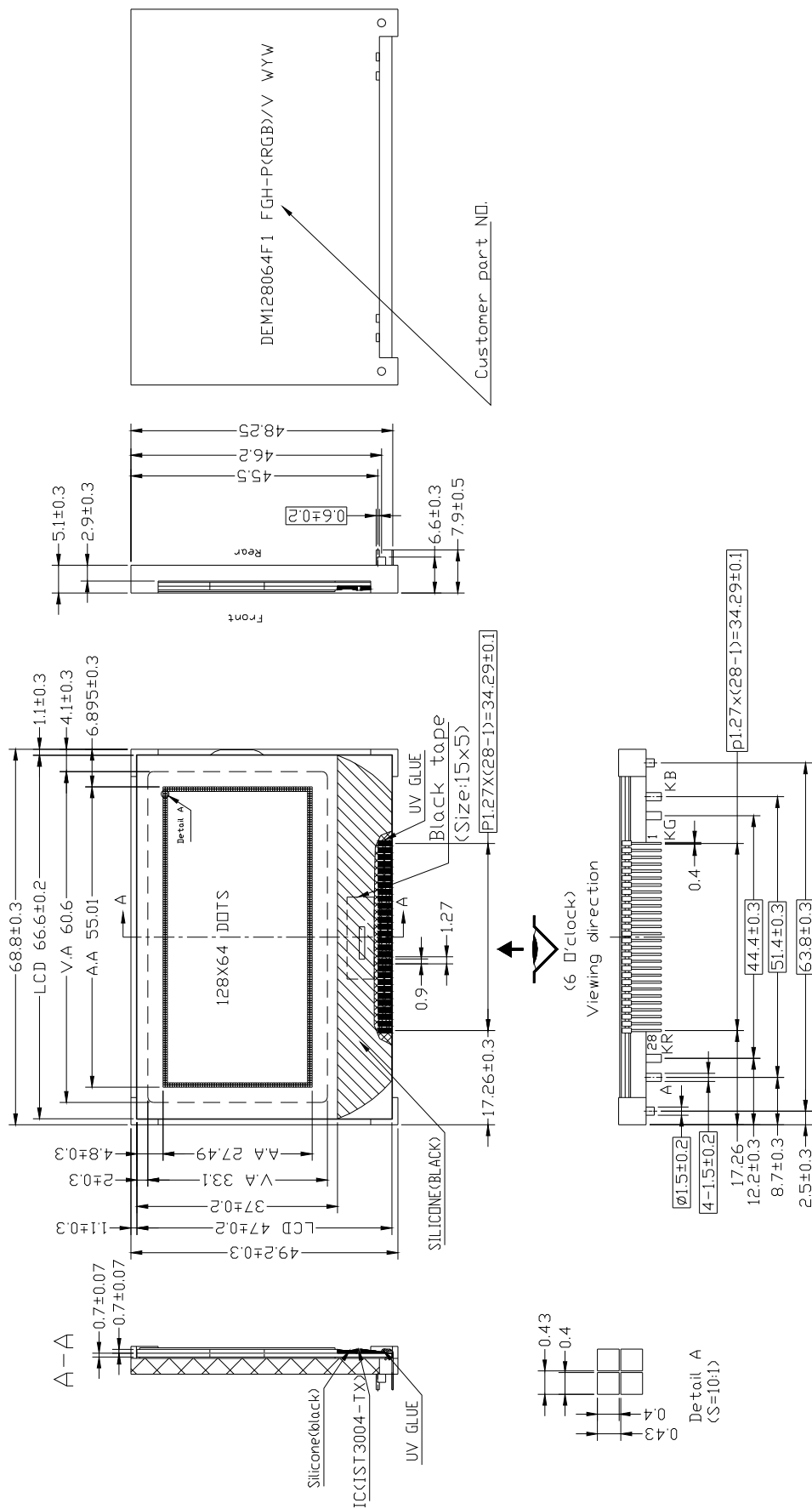
Module	LCD Type	Remarks
DEM 128064F1 FGH-P(RGB)	FSTN Transflective Positive Mode	

- I Viewing Direction : 6 O'clock
- I Driving Scheme : 1/65 Duty Cycle, 1/9 Bias
- I Power Supply Voltage(Typ.) : 3.0 V
- I V_{LCD} : 9.8 V
- I Display Contents :128x64 Dots
- I Interface : Parallel
- I Driver IC : IST3004-TX
- I RoHS Compliant

2. MECHANICAL SPECIFICATIONS

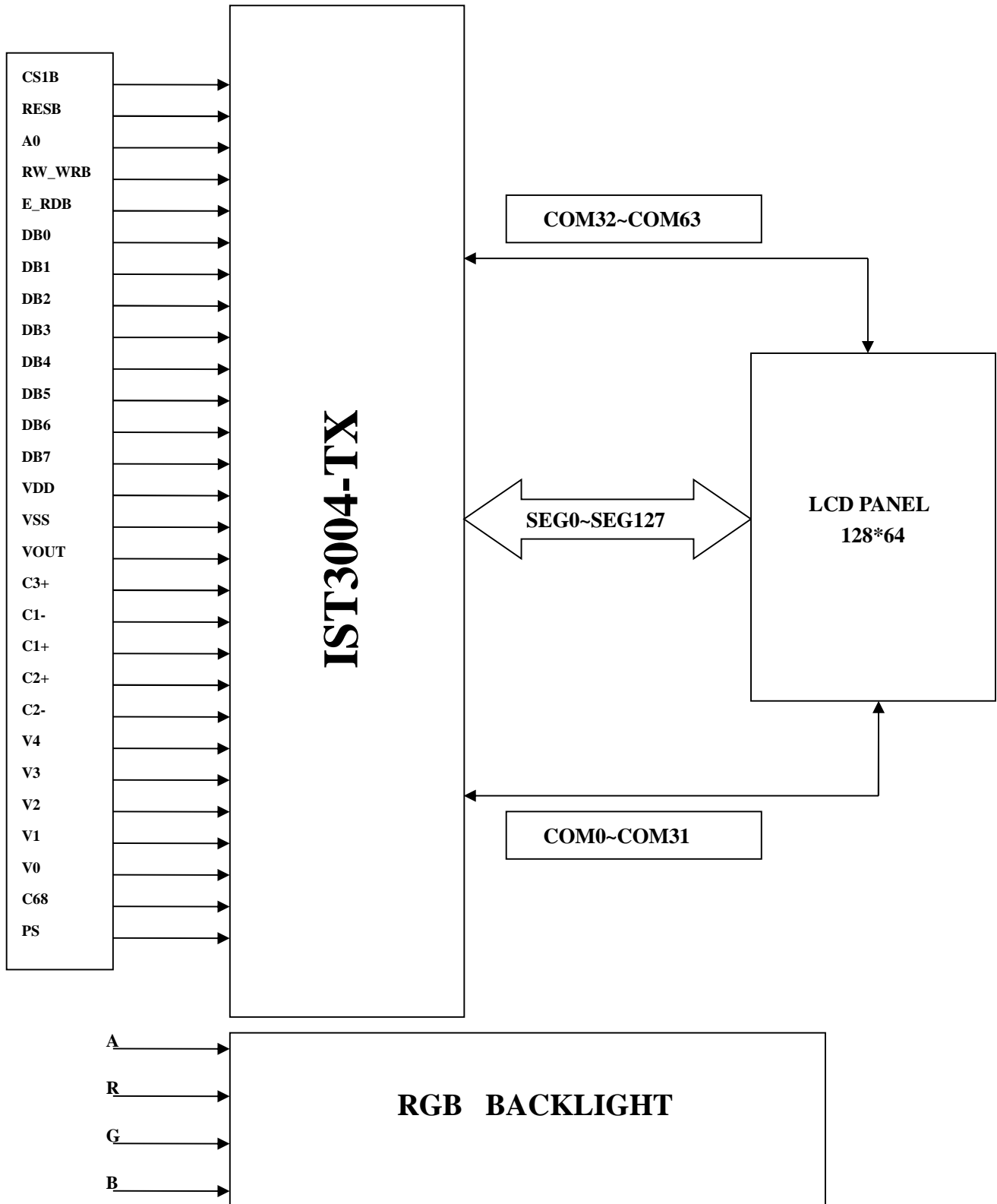
- I Module Size : 68.80 x 49.20 x 7.90mm
- I Viewing Area : 60.60 x 33.10mm
- I Active Area : 55.01 x 27.49mm
- I Dot pitch : 0.43 x 0.43mm
- I Dot Size : 0.40 x 0.40mm

3. EXTERNAL DIMENSIONS (unit: mm)



Remarks:
1. Unmarked tolerance is ± 0.30 ;
2. All material comply with RoHS.

4. BLOCK DIAGRAM



5. PIN DESCRIPTION

Pin No.	Name	I/O	Description												
1	CS1B	I	Chip select input pins Data / instruction I/O is enabled only when CS1B is "L" and CS2 is "H". when chip select is non-active, DB0 to DB7 may be high impedance												
2	RESB	I	Hardware Reset input pin When RESB is "L", initialization is executed.												
3	A0	I	Register select input pin - A0 = "H" : DB0 to DB7 are display data - A0 = "L" : DB0 to DB7 are control data												
4	RW_WRB	I	Read / Write execution control pin												
			<table border="1"> <thead> <tr> <th>C68</th> <th>MPU Type</th> <th>RW_WRB</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>H</td> <td>6800-series</td> <td>WR</td> <td>Read / Write control input pin - RW = "H" : read - RW = "L" : write</td> </tr> <tr> <td>L</td> <td>8080-series</td> <td>/WRB</td> <td>Write enable clock input pin The data on DB0 to DB7 are latched at the rising edge of the /WRB signal.</td> </tr> </tbody> </table>	C68	MPU Type	RW_WRB	Description	H	6800-series	WR	Read / Write control input pin - RW = "H" : read - RW = "L" : write	L	8080-series	/WRB	Write enable clock input pin The data on DB0 to DB7 are latched at the rising edge of the /WRB signal.
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5	E_RDB	I	Read / Write execution control pin												
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L	8080-series	/RDB	Read enable clock input pin When / RDB is "L", DB0 to DB7 are in an output status.												
6	DB0	I/O	8-bit bi-directional data bus that is connected to the standard 8-bit microprocessor data bus. When the serial interface selected (PS = "L"); - DB0 to DB5 : high impedance - DB6 : serial input clock (SCL) - DB7 : serial input data (SDI) When chip select is not active, DB0 to DB7 may be high impedance.												
7	DB1														
8	DB2														
9	DB3														
10	DB4														
11	DB5														
12	DB6														
13	DB7														
14	VDD	Supply	Power supply.												
15	VSS	Supply	Ground.												
16	Vout	Supply	DC/DC voltage converter												
17	C3+	O													
18	C1-	O													
19	C1+	O													
20	C2+	O													
21	C2-	O													
22	V4	Supply	LCD driver supply voltages The voltage determined by LCD pixel is impedance-converted by an operational amplifier for application. Voltages should have the following relationship; $V0 \geq V1 \geq V2 \geq V3 \geq V4 \geq VSS$ When the internal power circuit is active, these voltages are generated as following as following table according to the state of LCD bias.												
23	V3														
24	V2														
25	V1														
26	V0														
			<table border="1"> <thead> <tr> <th>LCD bias</th> <th>V1</th> <th>V2</th> <th>V3</th> <th>V4</th> </tr> </thead> <tbody> <tr> <td>1/9bias</td> <td>(8/9) xV0</td> <td>(7/9) xV0</td> <td>(2/9) xV0</td> <td>(1/9) xV0</td> </tr> </tbody> </table>	LCD bias	V1	V2	V3	V4	1/9bias	(8/9) xV0	(7/9) xV0	(2/9) xV0	(1/9) xV0		
LCD bias	V1	V2	V3	V4											
1/9bias	(8/9) xV0	(7/9) xV0	(2/9) xV0	(1/9) xV0											

27	C68	I	Microprocessor Interface Select input pin in parallel mode - C68 = "H" : 6800-series MPU interface - C68 = "L" : 8080-series MPU interface						
28	PS	I	Parallel / serial data input select input						
			PS	Interface Mode	Chip Select	Data / instruction	Data	Read / Write	Serial clock
			"H"	Parallel	CS1B	A0	DB0 to DB7	E_RDB RW_WRB	--
"L"	Serial	CS1B	A0	SDI (DB7)	Write only	SCL (DB6)			
<NOTE> In serial mode, it is impossible to read data from the on-chip RAM. And DB0 to DB5 and E_RDB and RW_WRB must be fixed to either "H" or "L".									

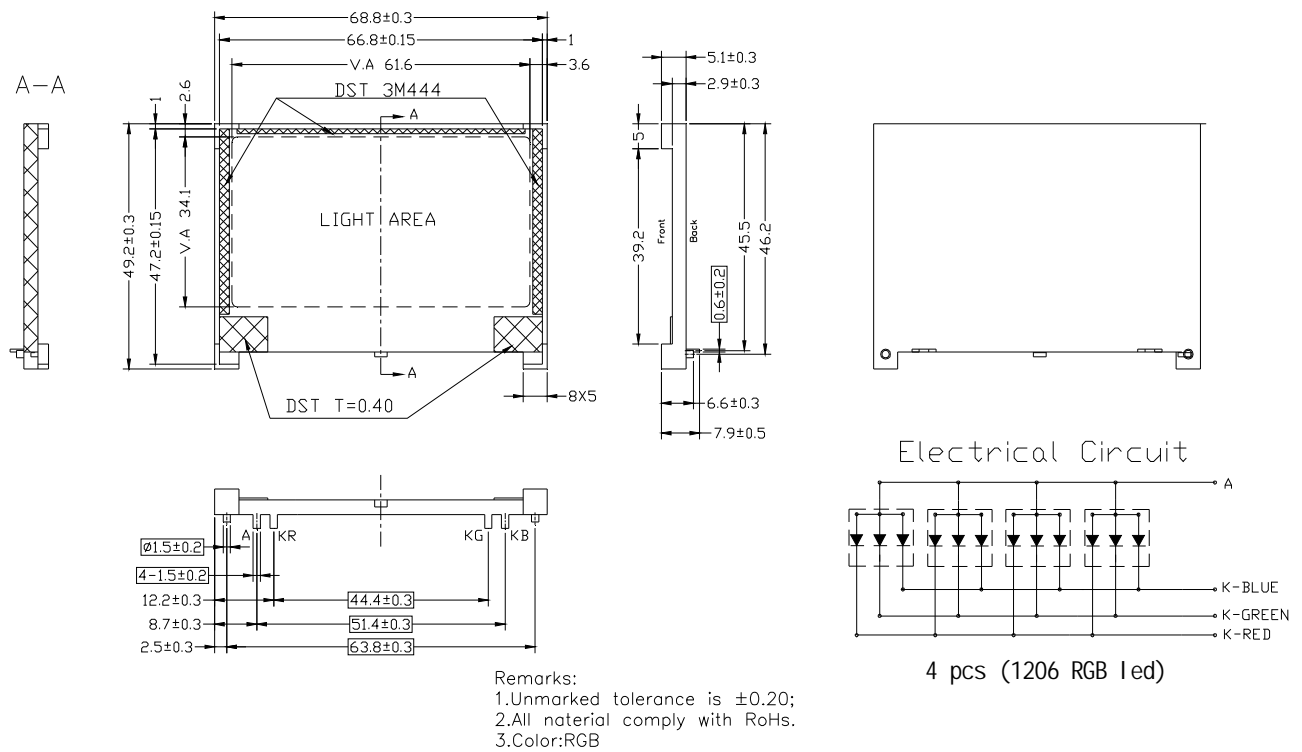
A	Anode of LED backlight
R	Cathode of RED LED backlight.
G	Cathode of GREEN LED backlight.
B	Cathode of BLUE LED backlight.

6. ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Unit
Power Supply Voltage	VDD	-0.3 ~ 7.0	V
Power Supply Voltage	V0, VOUT	-0.3 ~ 15.0	V
Power Supply Voltage	V1, V2, V3, V4	-0.3 to V0	V
Operating Temperature	TOPR	-20 to +70	°C
Storage Temperature	TSTR	-30 to +80	°C

7. BACKLIGHT CHARACTERISTICS

Item	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	Vf	R 1.7 G 2.8 B 2.8	R 2.0 G 3.2 B 3.2	R 2.4 G 3.4 B 3.4	V	RGB IF=80mA
Current	If		RGB IF=80mA		mA	
* Luminance	Lv		R 65 G 100 B 25		cd/m ²	
* Luminous Tolerance	ΔLv	70			%	Min/Max*100%
* Wavelength	λp	R 620 G 515 B 460	R 625 G 518 B 467	R 630 G 525 B 470	nm	RGB IF=80mA T=25°C



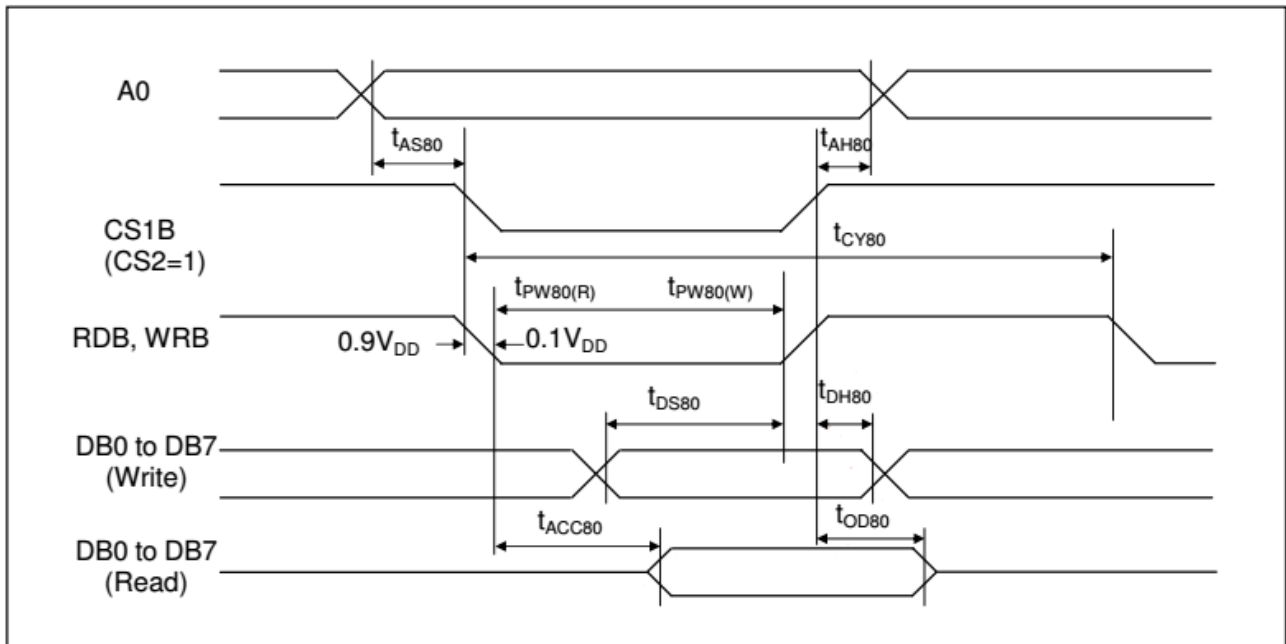
8. ELECTRICAL CHARACTERISTICS

8.1. DC CHARACTERISTICS

Item	Symbol	Condition	Standard Value			Unit
			Min.	Typ.	Max.	
Operating Voltage	V_{DD}	Relative to VSS	2.7	3.0	3.3	V
LCD Driving Voltage	V_{LCD}	Relative to VSS	9.6	9.8	10.0	
Consumption Current	I_{DD}	-	-	TBD	-	mA

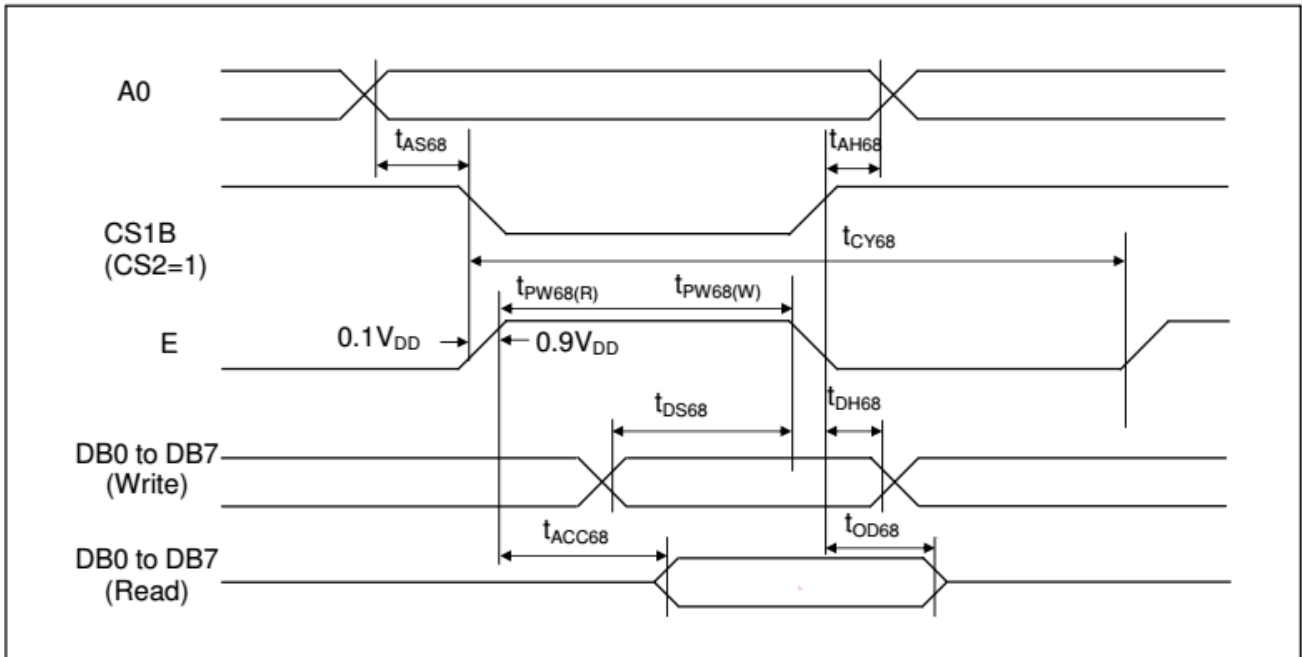
8.2. AC CHARACTERISTICS

Read / Write Characteristics (8080-series MPU)



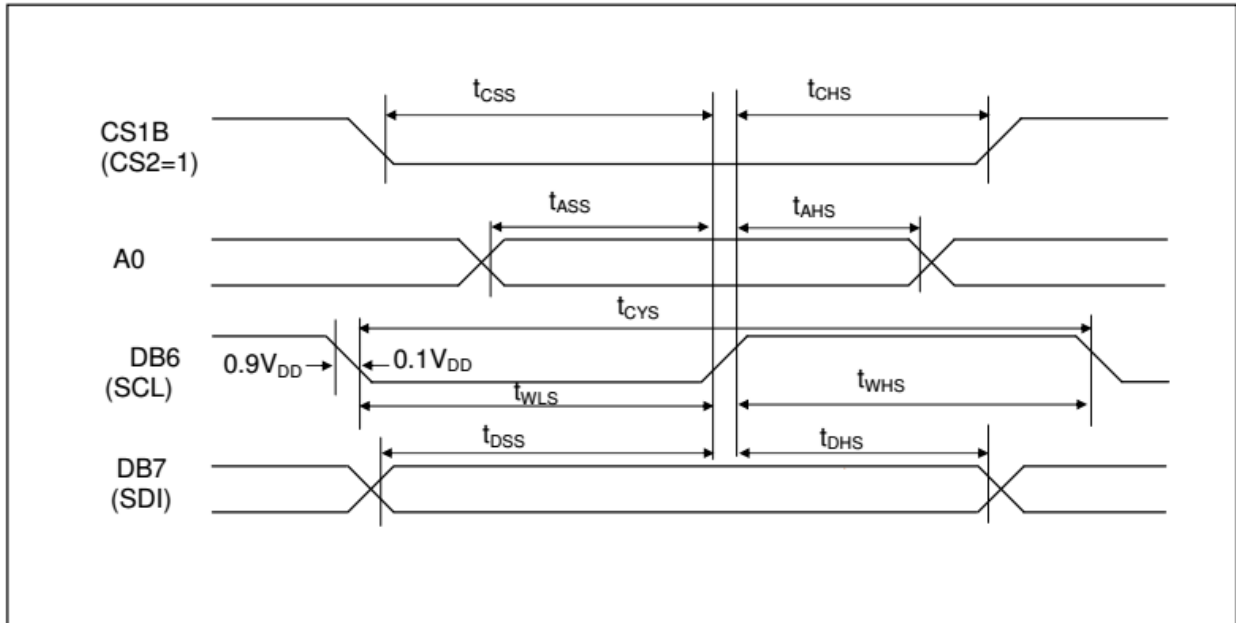
Item	Signal	Symbol	Min.	Typ.	Max.	Unit	Remark
Address setup time	A0	t_{AS80}	0	-	-	ns	
Address hold time	A0	t_{AH80}	0	-	-	ns	
System cycle time		t_{CY80}	300	-	-	ns	
Pulse width (WRB)	RW_WRB	$t_{PW80(W)}$	150	-	-	ns	
Pulse width (RDB)	E_RDB	$t_{PW80(R)}$	150	-	-	ns	
Data setup time	DB7 to DB0	t_{DS80}	60	-	-	ns	
Data hold time		t_{DH80}	0	-	-	ns	
Read access time	DB0	t_{ACC80}	140	-	-	ns	(No load)
Output disable time		t_{OD80}	-	-	10	ns	

Read / Write Characteristics (6800-series Microprocessor)



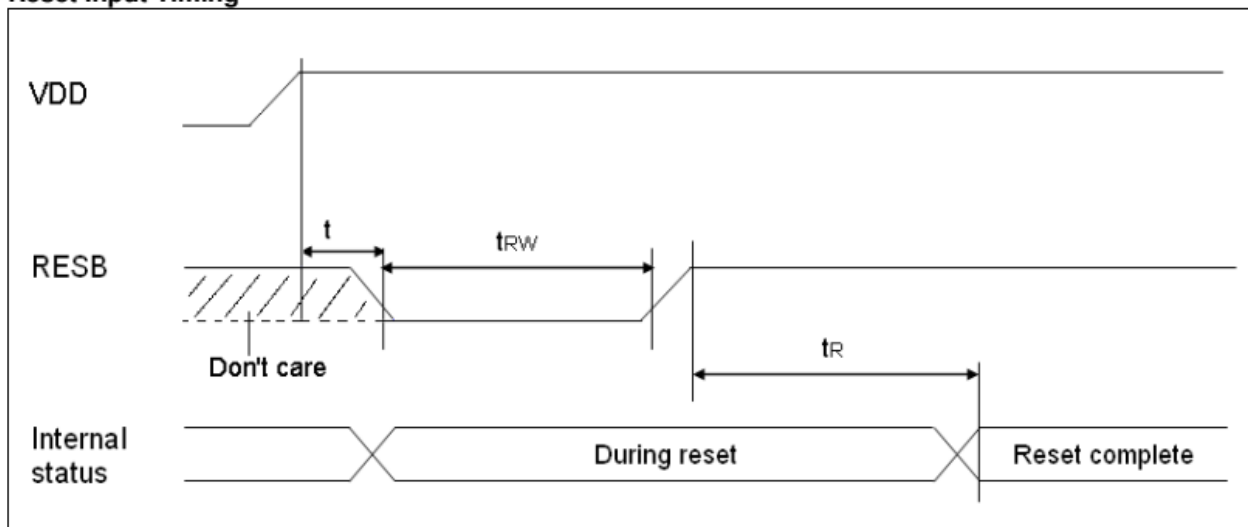
Item	Signal	Symbol	Min.	Typ.	Max.	Unit	Remark
Address setup time	A0		0	-	-	ns	
Address hold time		t_{AH68}	0	-	-	ns	
System cycle time		t_{CY68}	300	-	-	ns	
Pulse width (E)	RW_WRB	$t_{PW68(W)}$	150	-	-	ns	
Pulse width (E)	E_RDB	$t_{PW68(R)}$	150	-	-	ns	
Data setup time	DB7 to DB0	t_{DS68}	60	-	-	ns	
Data hold time		t_{DH68}	0	-	-	ns	
Read access time	DB0	t_{ACC68}	140	-	-	ns	(No load)
Output disable time		t_{OD68}	-	-	10	ns	

Serial Interface Characteristics



Item	Signal	Symbol	Min.	Typ.	Max.	Unit	Remark
Serial clock cycle	DB6 (SCL)	t_{CYS}	200	-	-	ns	
SCL high pulse width	DB6 (SCL)	t_{WHS}	90	-	-	ns	
SCL low pulse width	DB6 (SCL)	t_{WLS}	90	-	-	ns	
Address setup time	A0	t_{ASS}	45	-	-	ns	
Address hold time	A0	t_{AHS}	45	-	-	ns	
Data setup time	DB7 (SDI)	t_{DSS}	45	-	-	ns	
Data hold time	DB7 (SDI)	t_{DHS}	45	-	-	ns	
CS1B setup time	CS1B	t_{CSS}	90	-	-	ns	
CS1B hold time	CS1B	t_{CHS}	90	-	-	ns	

Reset Input Timing

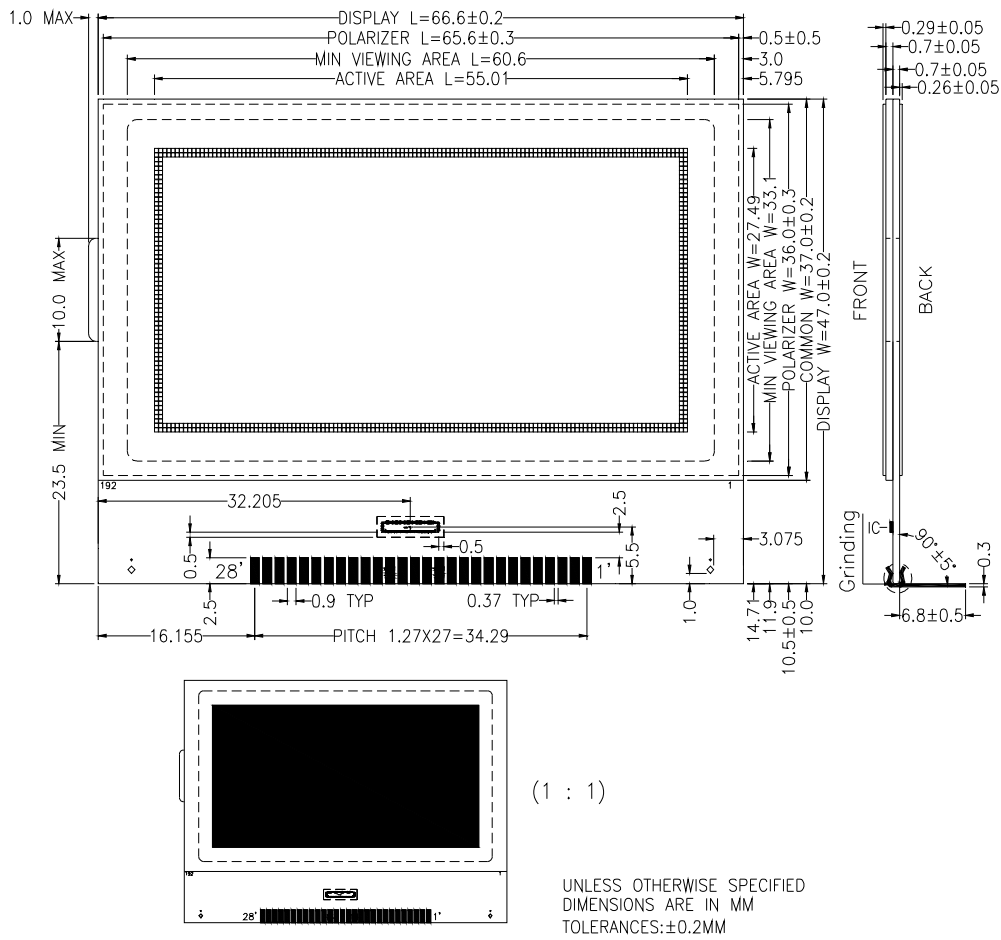


Item	Signal	Symbol	Min.	Typ.	Max.	Unit	Remark
Reset low pulse width	RESB	t _{RW}	2	-	-	us	
Reset time	-	t _R	-	-	2	us	
Reset time	RESB	t	0	-	-	us	

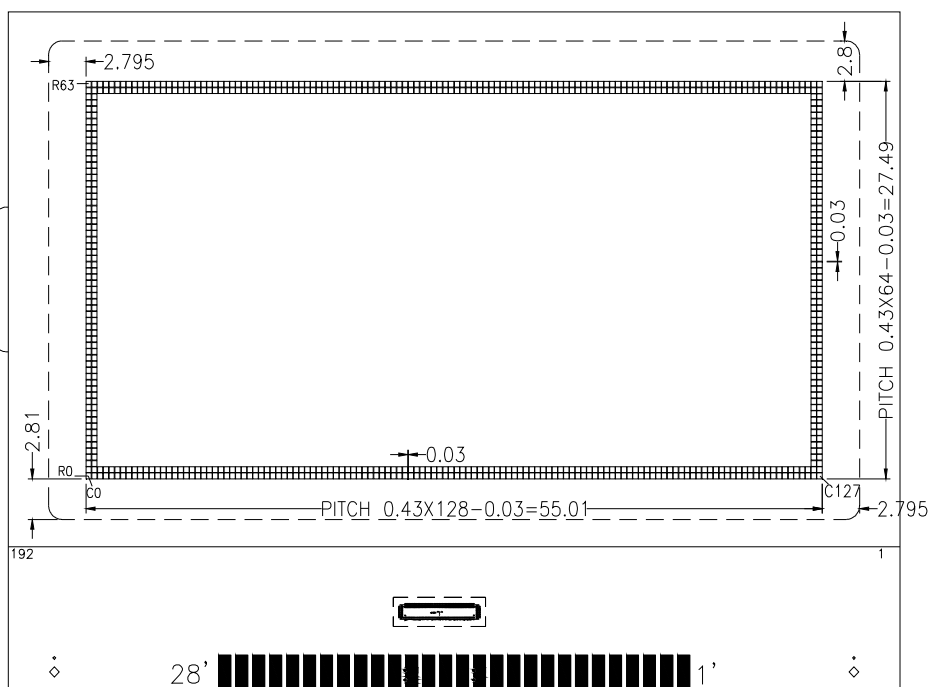
9. COMMAND TABLE

INSTRUCTION	A0	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description
Display ON / OFF	0	0	1	0	1	0	1	1	1	DON	LCD display On/Off control DON = 0 : display OFF DON = 1 : display On
Display starting line	0	0	0	1	ST5	ST4	ST3	ST2	ST1	ST0	Specify the line address for the first COM output
page address	0	0	1	0	1	1	P3	P2	P1	P0	Set page address
Set column address MSB	0	0	0	0	0	1	Y7	Y6	Y5	Y4	Set column address MSB
Set column address LSB	0	0	0	0	0	0	Y3	Y2	Y1	Y0	Set column address LSB
Read status	0	1	BUSY	ADC	ON/OFF	RESB	0	0	0	0	Read the internal status
Write display data	1	0	Write data								Write data into Display RAM
Read display data	1	1	Read data								Read data from Display RAM
ADC select	0	0	1	0	1	0	0	0	0	ADC	SEG output direction select ADC = 0 : SEG0 → SEG131 ADC = 1 : SEG131 → SEG0
Reverse display ON / OFF	0	0	1	0	1	0	0	1	1	REV	Normal / Reverse display select REV = 0 : Reverse display off REV = 1 : Reverse display on
Entire display ON / OFF	0	0	1	0	1	0	0	1	0	EON	Entire display On/Off control EON = 0 : Entire display off EON = 1 : Entire display on
LCD bias select	0	0	1	0	1	0	0	0	1	BS	Select LCD bias
Set Read-modify-write (RMW)	0	0	1	1	1	0	0	0	0	0	Set Read-modify-write mode
Clear RMW	0	0	1	1	1	0	1	1	1	0	Clear Read-modify-write mode
SW Reset	0	0	1	1	1	0	0	0	1	0	SW Reset
SHL select	0	0	1	1	0	0	SHL	x	x	x	COM output direction select SHL = 0 : COM0 → COM63 SHL = 1 : COM63 → COM0
Power control	0	0	0	0	1	0	1	VC	VR	VF	Control power circuit operation
Regulator resistor select	0	0	0	0	1	0	0	R2	R1	R0	Select internal resistance ratio of the regulator resistor
Set reference voltage mode	0	0	1	0	0	0	0	0	0	1	Set reference voltage mode (double byte command)
Set reference voltage register	0	0	x	x	SV5	SV4	SV3	SV2	SV1	SV0	Set reference voltage register
Set static indicator mode	0	0	1	0	1	0	1	1	0	SM	Set static indicator mode (double byte command)
Set static indicator register	0	0	x	x	x	x	x	x	S1	S0	Set static indicator register
Power save	-	-	-	-	-	-	-	-	-	-	Compound Instruction of display OFF and entire display ON
NOP	0	0	1	1	1	0	0	0	1	1	No operation (dummy command)
Set Booster Ratio select mode	0	0	1	1	1	1	1	0	0	0	Set Booster ration select mode (double byte command)
Set Booster Ratio register	0	0	x	x	x	x	x	x	BT1	BT0	Set Booster ration BT[1:0] = 00 : x2, x3, x4 BT[1:0] = 01 : x5 BT[1:0] = 11 : x6 BT[1:0] = 10 : (don't use)
Test Instruction	0	0	1	0	0	0	1	0	0	0	Test command (don't use)

10.LCD ARTWORK

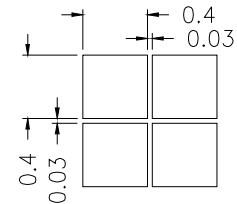


11.LABELLING



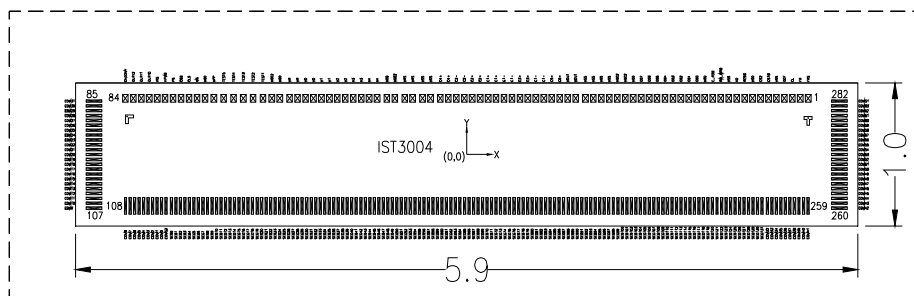
12. PAD CONFIGURATION& GRAPHIC DIMENSION

PAD NO.	IC NO.	PAD CONFIGURATION
1	COM63	COM63[R63(C0-C127)]
2	COM62	COM62[R62(C0-C127)]
31	COM33	COM33[R33(C0-C127)]
32	COM32	COM32[R32(C0-C127)]
33	SEG127	SEG127[C127(R0-R63)]
34	SEG126	SEG126[C126(R0-R63)]
159	SEG1	SEG1[C1(R0-R63)]
160	SEG0	SEG0[C0(R0-R63)]
161	COM0	COM0[R0(C0-C127)]
162	COM1	COM1[R1(C0-C127)]
191	COM30	COM30[R30(C0-C127)]
192	COM31	COM31[R31(C0-C127)]



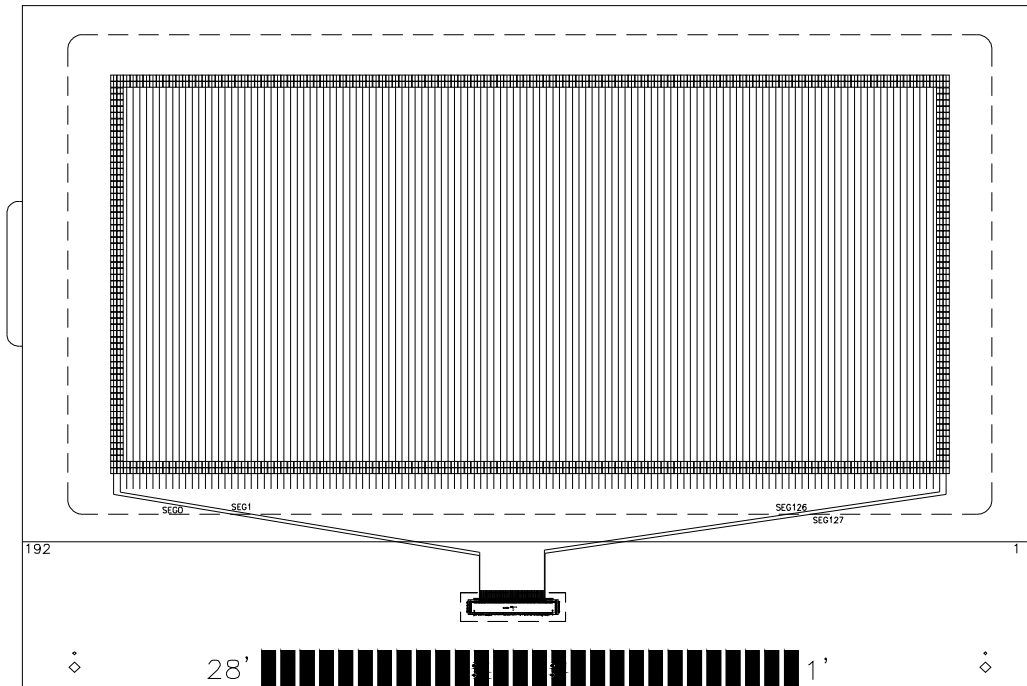
UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MM
TOLERANCES:±0.1MM

13. IC NO. CONFIGURATION& PAD CONFIGURATION

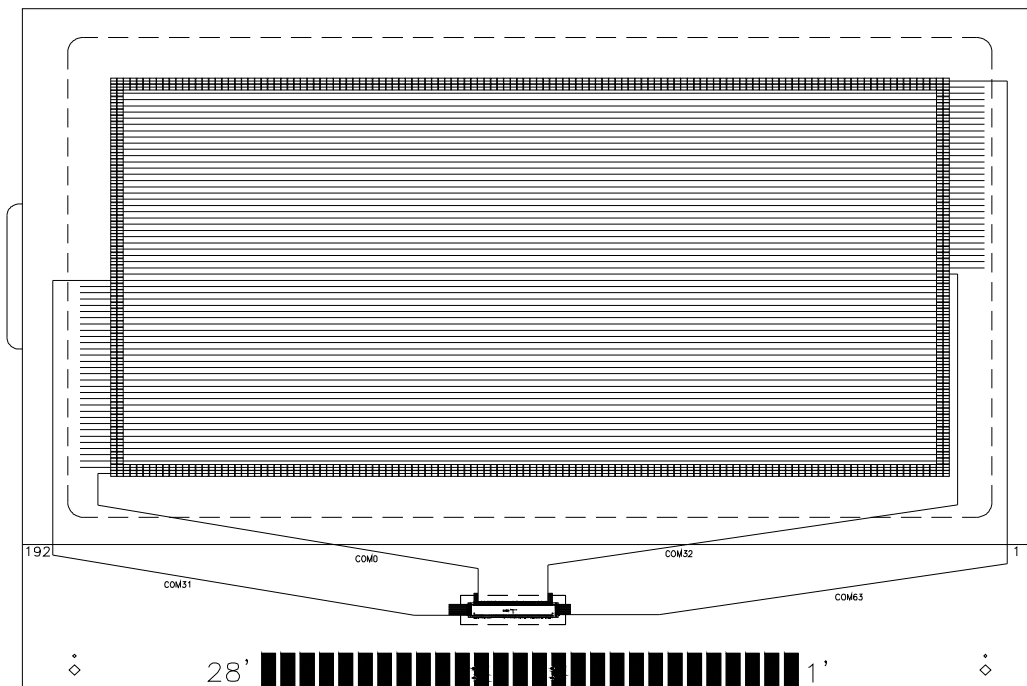


PAD NO.	PAD CONFIGURATION	PAD NO.	PAD CONFIGURATION
1	CS1B	15	VSS,DUTY0,DUTY1,DUTY2,GNDDMY,HPMB
2	RESB	16	VOUT
3	A0	17	C3+
4	RW_WRB	18	C1-
5	E_RDB	19	C1+
6	DB0	20	C2+
7	DB1	21	C2-
8	DB2	22	V4
9	DB3	23	V3
10	DB4	24	V2
11	DB5	25	V1
12	DB6	26	V0
13	DB7	27	C68
14	VDD2,VDD	28	PS

14. SEG&COM LAYOUT

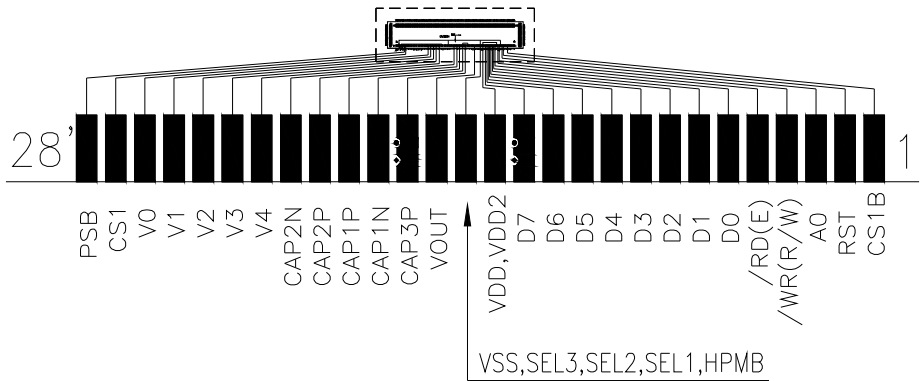


SEG



COM

15. IC LAYOUT

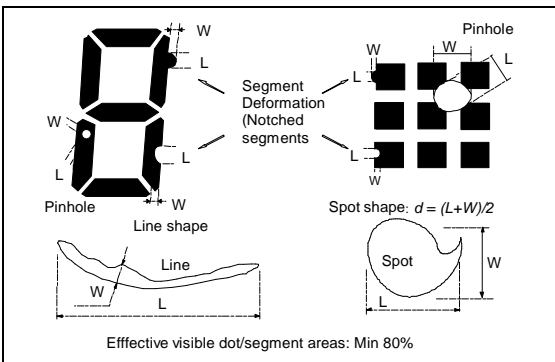


16. QUALITY DESCRIPTION

DEFECT SPECIFICATION:

Specific type-related items are covered in this sheet.

- a: Table for Cosmetic defects
(Note: nc = not counted).
Sizes and number of defects
(Max. Qty)

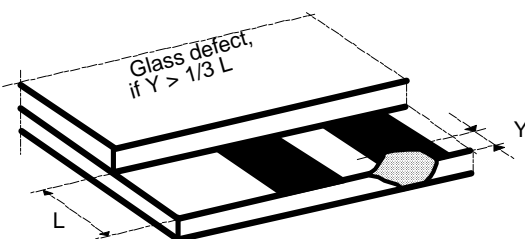


Examples/ Shapes

b: Glass defects

b1: Glass defects at contact ledge

b2: Glass chipping in other areas shall not be in conflict with the product's function.



Defect Type	Max. defect size [mm] d or L W	Max. Quantity.
Black or White Spots	$d \leq 150$	nc
	$150 < d \leq 300$	5
Black or White Lines	$W \leq 10$	nc
	$L \leq 5000$ $W \leq 30$	3
Pinhole	$L \leq 2000$ $W \leq 50$	2
	$d \leq 150$ $150 < d \leq 300$	nc 1/segment
(Total defects)		(5)
Segment Deformation	$W \leq 100$	nc
Bubble (e.g. under pola)	$d \leq 150$	nc
	$200 < d \leq 400$	3
	$400 < d \leq 600$	1

17. MODULE ACCEPTS QUALITY LEVEL (AQL).

17.1. AQL standard value: Critical defect =0.1, Major defect=0.65; Minor defect =2.5.

17.2. Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level II.

18. RELIABILITY TEST

Operating life time: 50,000 hours

(at room temperature without direct irradiation of sunlight)

Reliability characteristics shall meet following requirements.

Tests Item	Condition
High Temperature Storage	+80°C x 96HR
Low Temperature Storage	-30°C x 96HR
High Temperature Operation	+70°C x 96HR
Low Temperature Operation	-20°C x 96HR
High Temperature, High Humidity	+60°C x 90%RH x 96HR
Thermal Shock	-20°C x 30min à 25°C x 10s à +70°C x 30 min x 5 cycles
Vibration Test	Frequency x Swing x Time 40Hz x 4mm x 4hrs
Drop Test	Height x no. of drop 1.0m x 6 drops

19. LCD MODULES HANDLING PRECAUTIONS

- n** The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- n** If the display panel is damaged and the liquid crystal substance inside it leaks out, do not get any in your mouth. If the substance come into contact with your skin or clothes promptly wash it off using soap and water.
- n** Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- n** The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarize carefully.
- n** To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling the LCD module.
 - Tools required for assembly, such as soldering irons, must be properly grounded.
 - To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- n** Storage precautions
When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags designed to prevent static electricity charging (or in bags designed to prevent static electricity charging) under low temperature / normal humidity conditions (avoid high temperature / high humidity and low temperatures below -20°C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

20. OTHERS

- n** Liquid crystals solidify at low temperature (below the storage temperature range) leading to defective orientation of liquid crystal or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subjected to a strong shock at a low temperature.
- n** If the LCD modules have been operating for a long time showing the same display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. Abnormal operating status can be resumed to be normal condition by suspending use for some time. It should be noted that this phenomena does not adversely affect performance reliability.
- n** To minimize the performance degradation of the LCD modules resulting from caused by static electricity, etc. exercise care to avoid holding the following sections when handling the modules:
 - Exposed area of the printed circuit board
 - Terminal electrode sections